



RoHS Compliant

**MAX
260°C**

**MSL
1**



PRODUCT FAMILY	Material	CAS Number	% Normalize for BOM	Wt. Of BOM Item (g)	% by Wt (Comp. Item)	mg/unit	% by Wt Of Unit 156.50	ppm
766 14								
Alumina Ceramic	Al2O3	1344-28-1	0.8750	0.1369	87.50%	119.8203	76.56%	765625
	SiO2 (silicon dioxide)	14808-60-7			12.50%	17.1172	10.94%	109375
Conductor Thick Film	Ag	7440-22-4	0.0059	0.0009	99.00%	0.9141	0.58%	5841
	Pd	7440-05-3			1.00%	0.0092	0.01%	59
Resistor Thick Film	RuO2	12036-10-1	0.0074	0.0012	30.00%	0.3474	0.22%	2220
	PbO	1317-36-8			10.00%	0.1158	0.07%	740
	SiO2 (silicon dioxide)	14808-60-7			30.00%	0.3474	0.22%	2220
	B2O3	1303-86-2			30.00%	0.3474	0.22%	2220
Notch Conductor Thick Film	Ag	7440-22-4	0.0112	0.0018	72.02%	1.2624	0.81%	8066
	Pd	7440-05-3			4.20%	0.0736	0.05%	470
	Pt	7440-06-4			23.78%	0.4168	0.27%	2663
					100.00%	1.7528		
Lead Wire	Cu	7440-50-8	0.0360	0.0056	100.00%	5.6340	3.60%	36000
Lead Under-Plating	Ni	7440-02-0	0.0100	0.0016	100.00%	1.5650	1.00%	10000
Solder	Ag	7440-22-4	0.0360	0.0056	3.00%	0.1690	0.11%	1080
	Cu	7440-50-8			0.50%	0.0282	0.02%	180
	Sn	7440-31-5			96.50%	5.4368	3.47%	34740
Covercoat	TiO2	13463-67-7	0.0185	0.0029	50.00%	1.4476	0.93%	9250
	Phenolic Resin	55185-45-0			25.00%	0.7238	0.46%	4625
	Epoxy Resin	25068-38-6			25.00%	0.7238	0.46%	4625
	Sum		1.0000 part weight	0.1565	100.00%	2.8953		
		Totals:		0.1565		156.50	100.00%	1000000

RoHS exemption claimed for lead in glass of electronic component